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#### 300V NPN MEDIUM POWER HIGH VOLTAGE TRANSISTOR IN SOT223

#### **Features**

- BV<sub>CEO</sub> > 300V
- BV<sub>CBO</sub> > 300V
- I<sub>C</sub> = 0.5A High Continuous Current
- I<sub>CM</sub> = 1A Peak Pulse Current
- Complementary PNP Type: FZT757
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

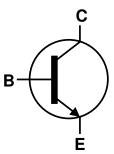
#### **Mechanical Data**

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound;
   UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 <sup>3</sup>
- Weight: 0.112 grams (Approximate)

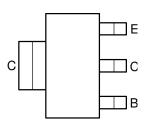




Top View



Device Symbol



Top View Pin-Out

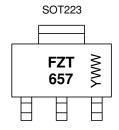
### Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FZT657TA	AEC-Q101	FZT657	7	12	1,000
FZT657QTA	Automotive	FZT657	7	12	1,000

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_compliance\_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

#### **Marking Information**



FZT 657 = Product Type Marking Code YWW = Date Code Marking Y or  $\overline{Y}$  = Last Digit of Year (ex: 5= 2015) WW or  $\overline{W}W$  = Week Code (01~53)





**FZT657** 

## Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	300	V
Collector-Emitter Voltage	$V_{\sf CEO}$	300	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	V
Continuous Collector Current	Ic	0.5	Α
Peak Pulse Current	I <sub>CM</sub>	1	Α

### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
	(Note 6)		3.0		
Power Dissipation	(Note 7)	Ь	2.0	W	
Power Dissipation	(Note 8)	$P_D$	1.6		
	(Note 9)		1.2	ļ	
	(Note 6)		41.7		
Thermal Resistance, Junction to Ambient	(Note 7)	В	62.5		
Thermal Resistance, Junction to Ambient	(Note 8)	$R_{ hetaJA}$	78.1	°C/W	
	(Note 9)		104	1	
Thermal Resistance Junction to Lead (Note 10)		$R_{ heta JL}$	12.9		
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C		

### ESD Ratings (Note 11)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

- 6. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

- 7. Same as Note 6, except the device is mounted on 25mm x 25mm 2oz copper.

  8. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.

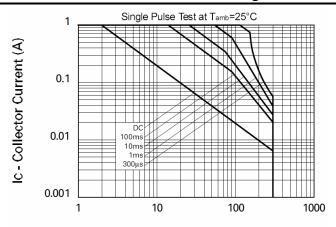
  9. Same as Note 6, except the device is mounted on minimum recommended pad layout.

  10. Thermal resistance from junction to solder-point (at the end of the collector lead).

  11. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

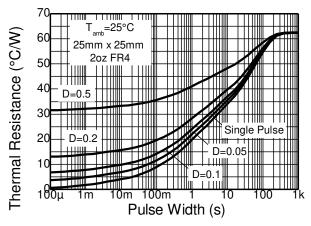


### **Thermal Characteristics and Derating Information**

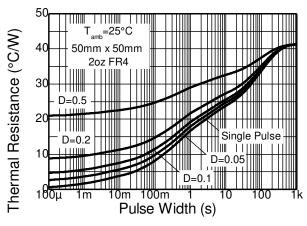


VCE - Collector Emitter Voltage (V)

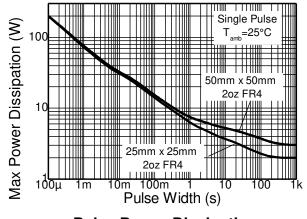
### Safe Operating Area



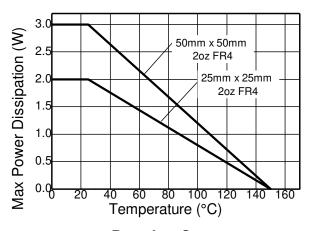
**Transient Thermal Impedance** 



**Transient Thermal Impedance** 



**Pulse Power Dissipation** 



**Derating Curve** 





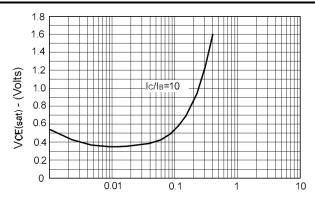
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	300	_	_	V	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV <sub>CEO</sub>	300	_	_	V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	_	_	V	$I_E = 100\mu A$
Collector-Base Cut-Off Current	I <sub>CBO</sub>	_	_	100	nA	V <sub>CB</sub> = 200V
Emitter Cut-Off Current	I <sub>EBO</sub>	1	_	100	nA	$V_{EB} = 5.6V$
DC Current Gain (Note 12)	h	40	_	_		$I_C = 10mA, V_{CE} = 5V$
Do dullent dain (Note 12)	h <sub>FE</sub>	50	_	_		$I_C = 100 \text{mA}, V_{CE} = 5 \text{V}$
Collector-Emitter Saturation Voltage (Note 12)	V <sub>CE(sat)</sub>	1	_	0.5	V	$I_C = 100 \text{mA}, I_B = 10 \text{mA}$
Base-Emitter Saturation Voltage (Note 12)	V <sub>BE(sat)</sub>	1	_	1.0	V	$I_C = 100 \text{mA}, I_B = 10 \text{mA}$
Base-Emitter Turn-On Voltage (Note 12)	V <sub>BE(on)</sub>	_	_	1.0	V	$I_C = 100 \text{mA}, V_{CE} = 5 \text{V}$
Output Capacitance	C <sub>obo</sub>	_	_	20	pF	$V_{CB} = 20V, f = 1MHz$
Current Gain-Bandwidth Product	f⊤	30	_	_	MHz	V <sub>CE</sub> = 20V, I <sub>C</sub> = 10mA, f=20MHz

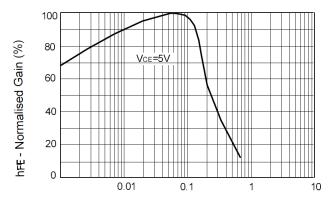
Note: 12. Measured under pulsed conditions. Pulse width  $\leq$  300  $\mu$ s. Duty cycle  $\leq$  2%.



## Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

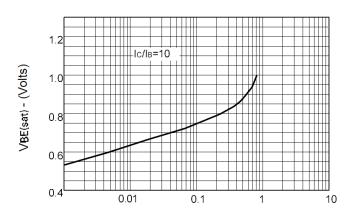


Ic - Collector Current (Amps)



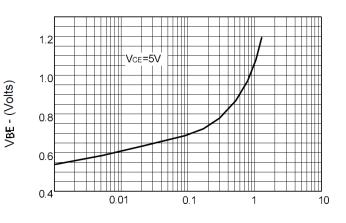
Ic - Collector Current (Amps)

#### VCE(sat) v IC



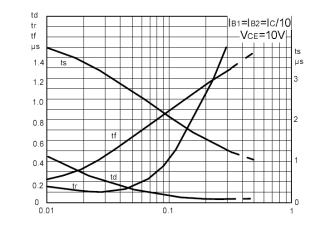
Ic - Collector Current (Amps)

#### hFE v IC



Ic - Collector Current (Amps)

### VBE(sat) v IC



Ic - Collector Current (Amps)

## **Switching Speeds**

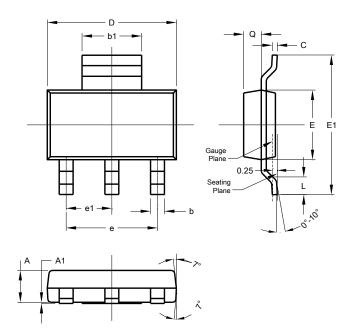
# VBE(on) v IC

Switching time



### **Package Outline Dimensions**

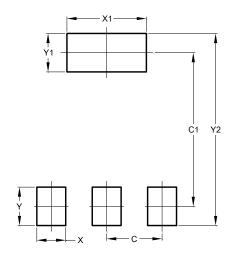
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.30
C1	6.40
X	1.20
X1	3.30
Υ	1.60
Y1	1.60
Y2	8.00

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.





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